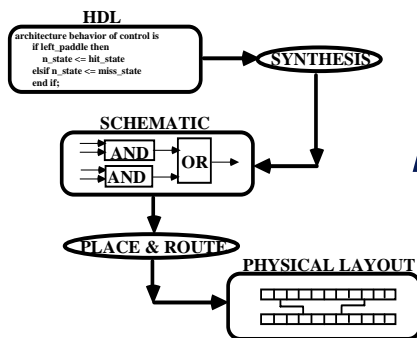


DESIGNING ASICS

ECE 651 Overview

Prof. Don Bouldin, Ph.D.



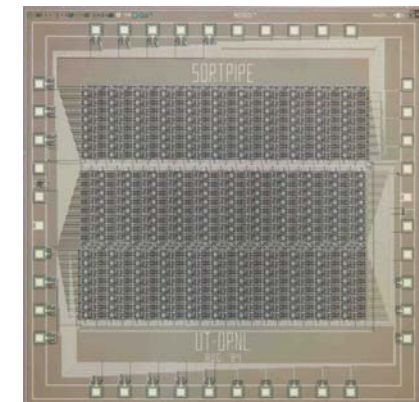
Electrical & Computer Engineering

University of Tennessee

TEL: (865)-974-5444

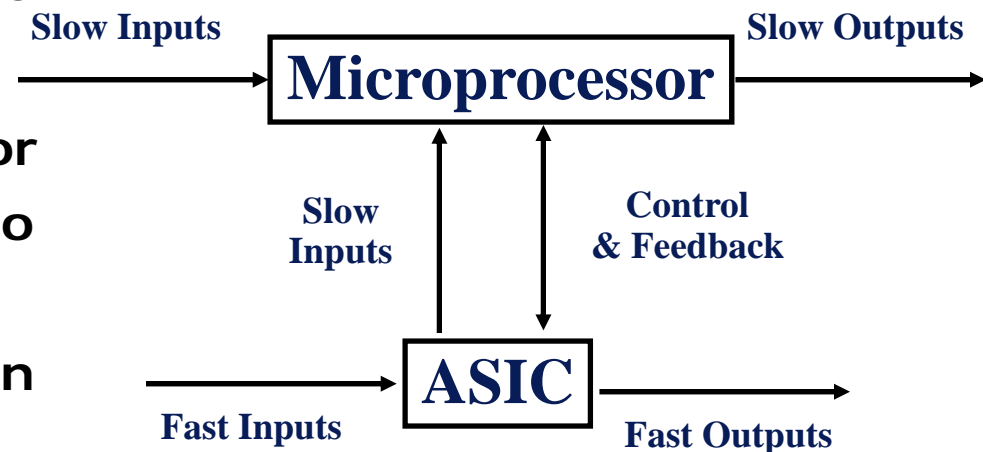
FAX: (865)-974-5483

dbouldin@tennessee.edu

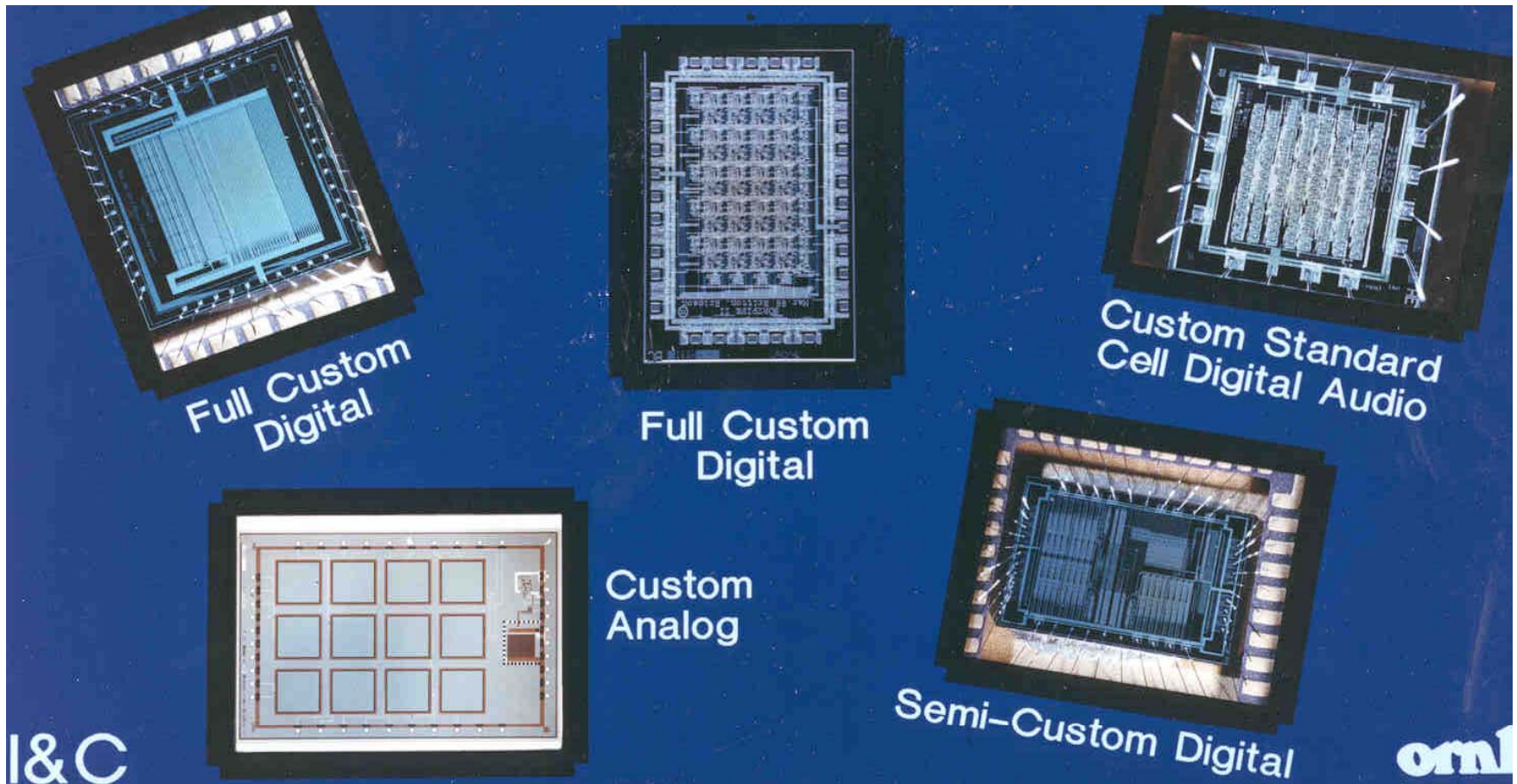


SYSTEM FUNCTIONS ARE OFTEN SPLIT BETWEEN THE CPU AND AN ASIC

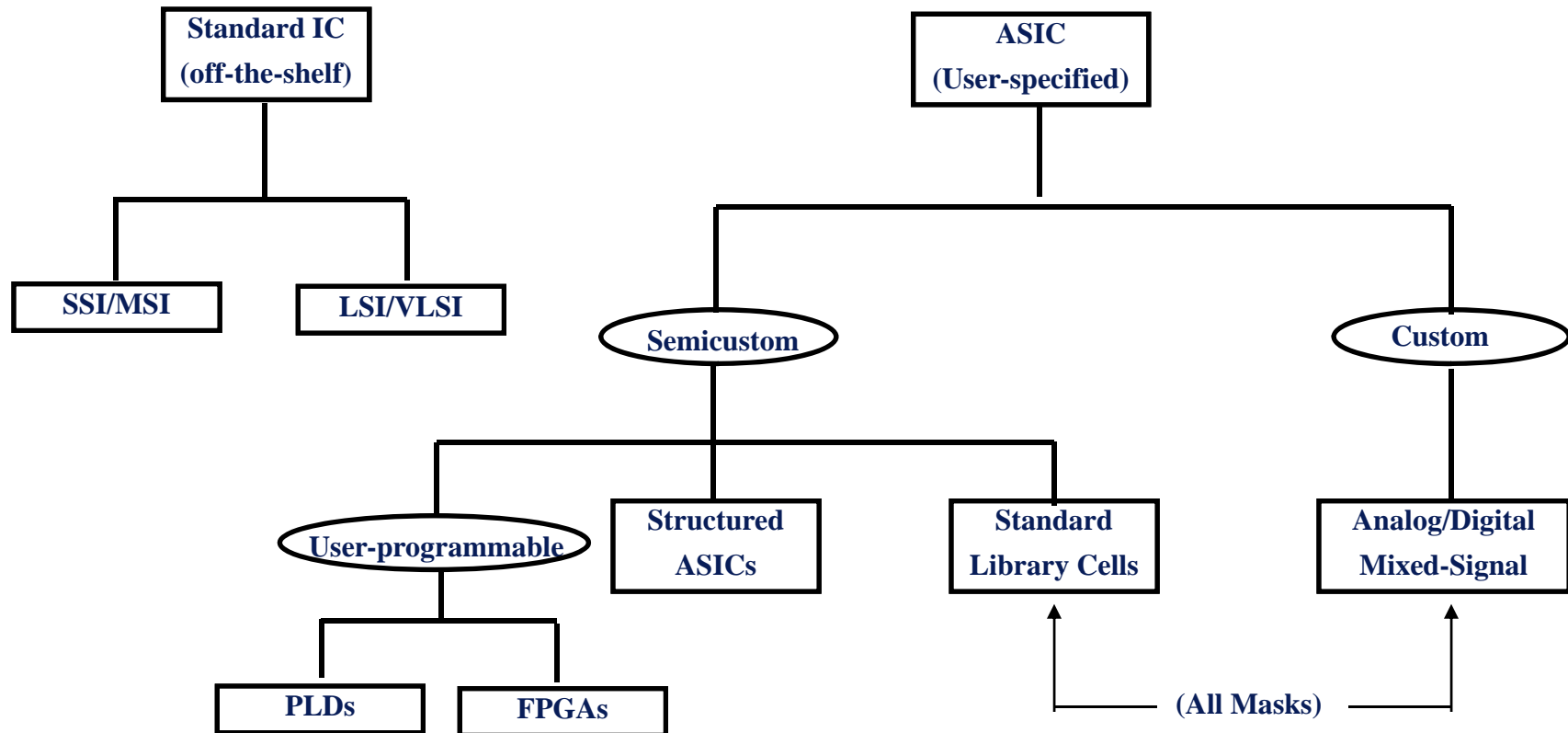
- The most economical means of implementing logic functions is to use a microprocessor.
- When the microprocessor is too slow or too busy to handle some fast inputs and outputs, an ASIC can be used to implement high-speed concurrent operations.



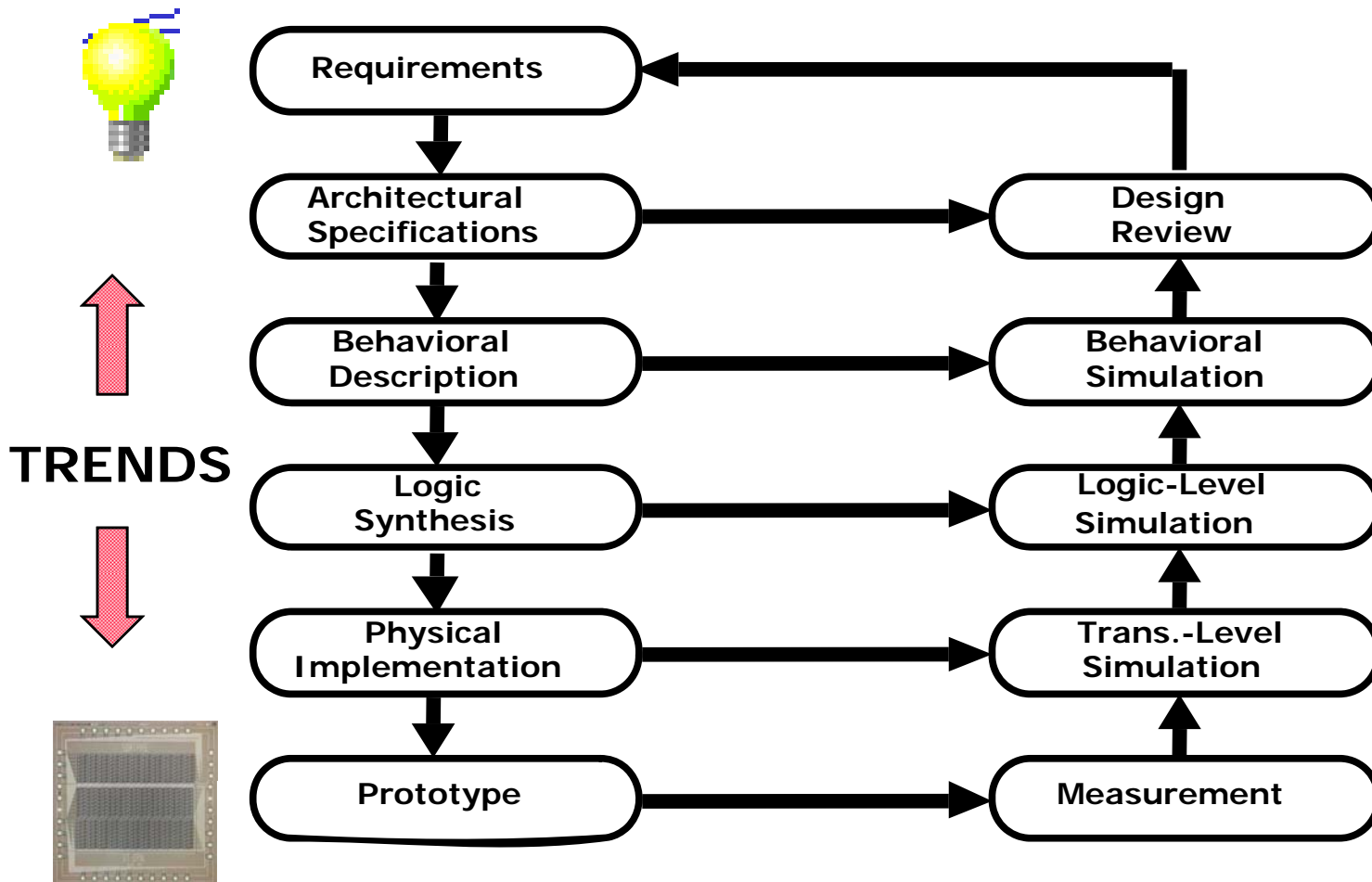
A VARIETY OF ICS ARE POSSIBLE



APPLICATIONS MAY USE STANDARD ICs or FPGAs/ASICs



MICROELECTRONIC SYSTEM DESIGN CONSISTS OF ITERATIVE REFINEMENTS OF SYNTHESIS AND VERIFICATION



ECE 551 & ECE 651

- **ECE 551 (logic level; b/w):**
 - Pairs create project using VHDL
 - Simulate pre-synthesis and post-layout
 - Demonstrate using 200K-gate Xilinx FPGA on Spartan3 Board with I/O
 - Implement on screen only using Altera FPGA
- **ECE 651 (physical level; color):**
 - Perform custom IC design (but not submit for fab)
 - Compare manual design vs. automated tools
 - Study nanometer design issues (cross-talk, power)

FAB FOUNDRIES COST BILLIONS

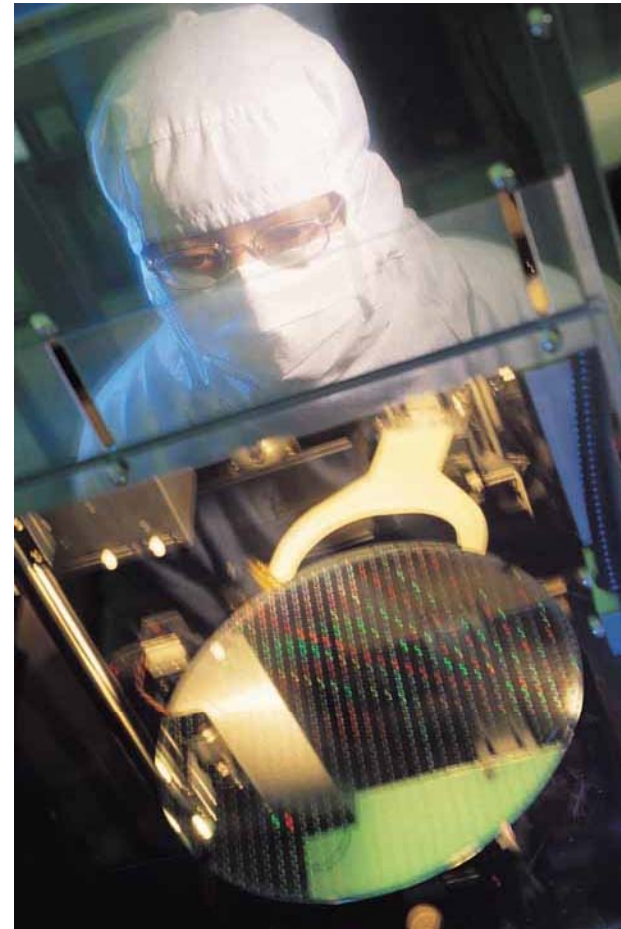
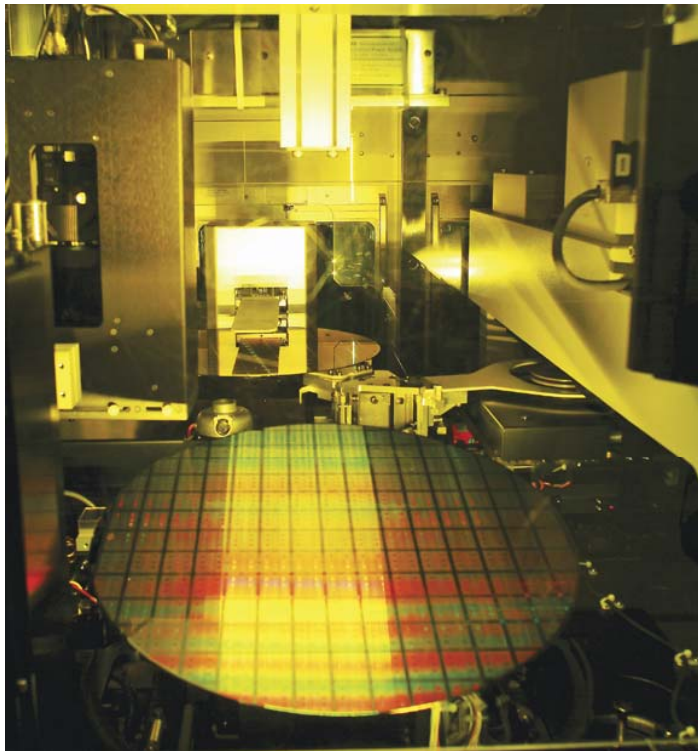
- Intel spent \$3 billion to construct and equip its integrated circuit fabrication facility in Chandler, Arizona.
- The foundry produces 300-mm wafers using feature sizes of 45 nanometers.



<http://www.intel.com/>

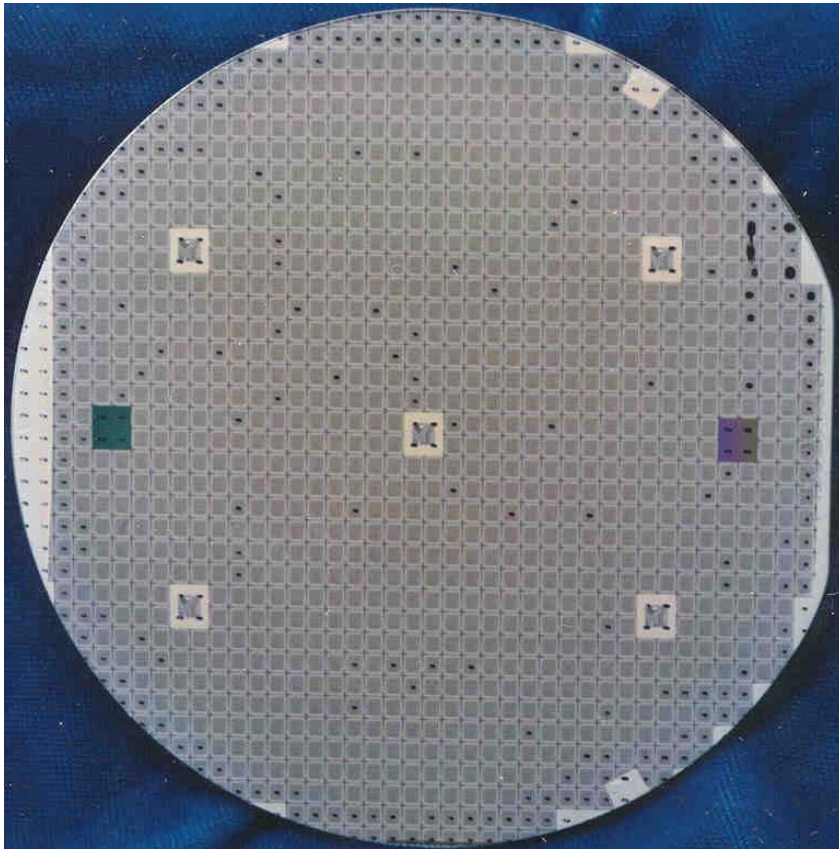
MASK CHARGES COST MILLIONS

- According to SemaTech, a mask set for 65-nm costs \$3 million.

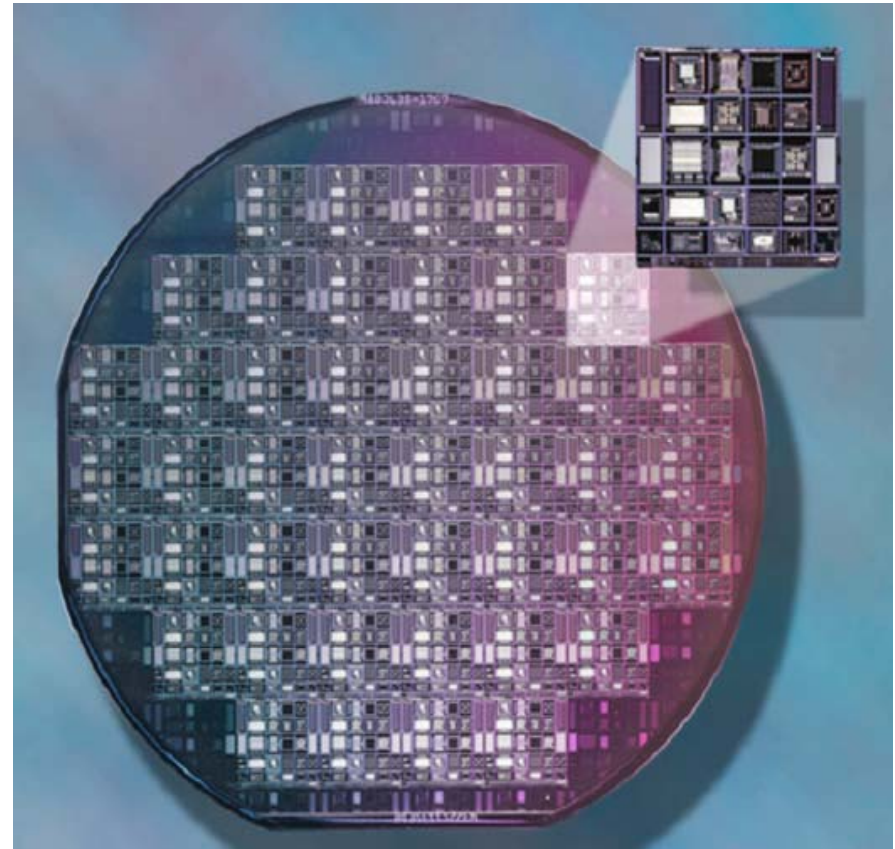


<http://www.tsmc.com/>

SHARING MASK/WAFER COSTS



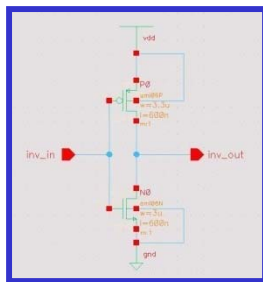
<http://www.ssec.honeywell.com/>



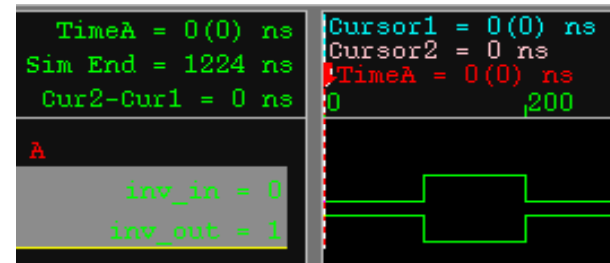
<http://www.mosis.org/>

CUSTOM IC DESIGN FLOW

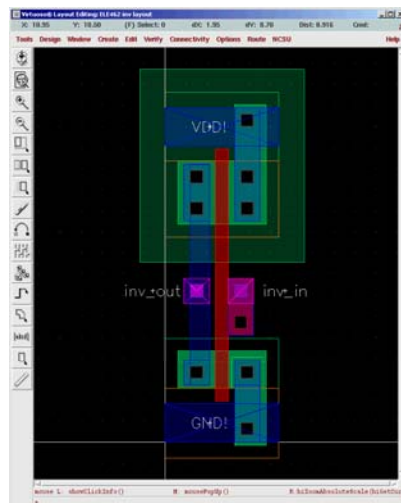
1--SCHEMATIC



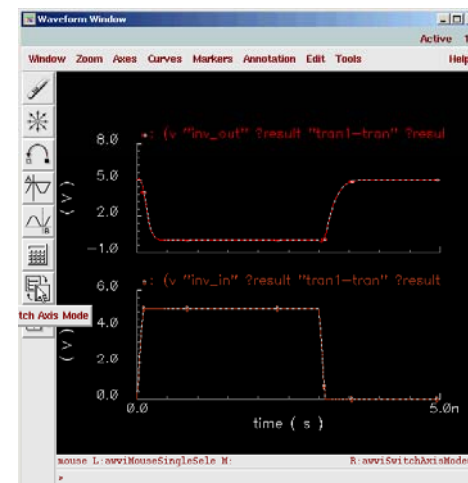
2--PRE-LAYOUT LOGIC SIMULATION



3--MANUAL LAYOUT

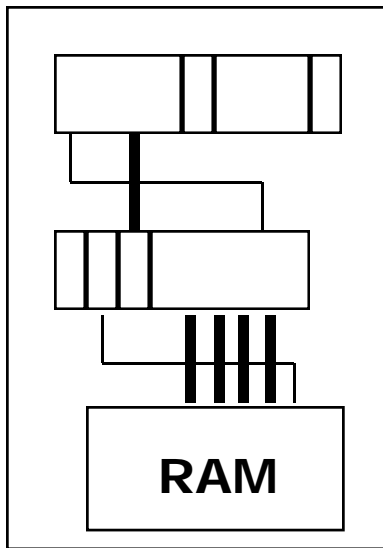


4--POST-LAYOUT TRANS. SIMULATION



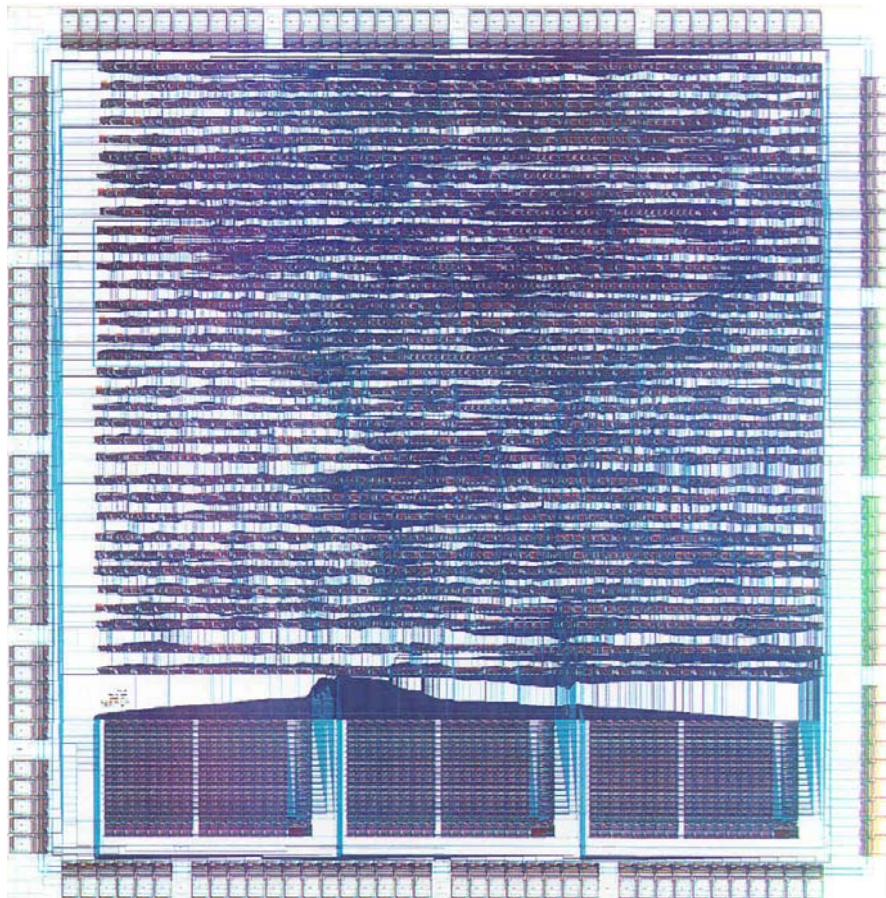
STANDARD-CELLS ARE BEST FOR HIGH-QUANTITY APPLICATIONS WITH RAM

Standard-Height Library Cells

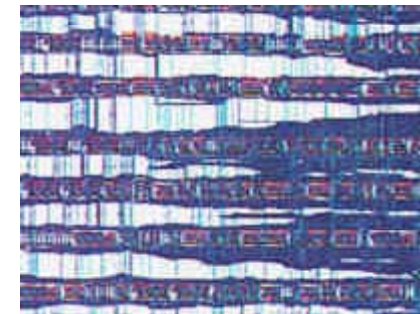


- Vendor develops library disk files of logic functions (and internal RAM or cache).
- User selects cells and specifies *two* layers of interconnections
- After place & route, masks are made for *all* layers
- Replaces 20,000 to 2,000,000 gates (or more)
- Workstation-based development system costs more than \$ 200K
- Turnaround time for prototypes is 8 weeks

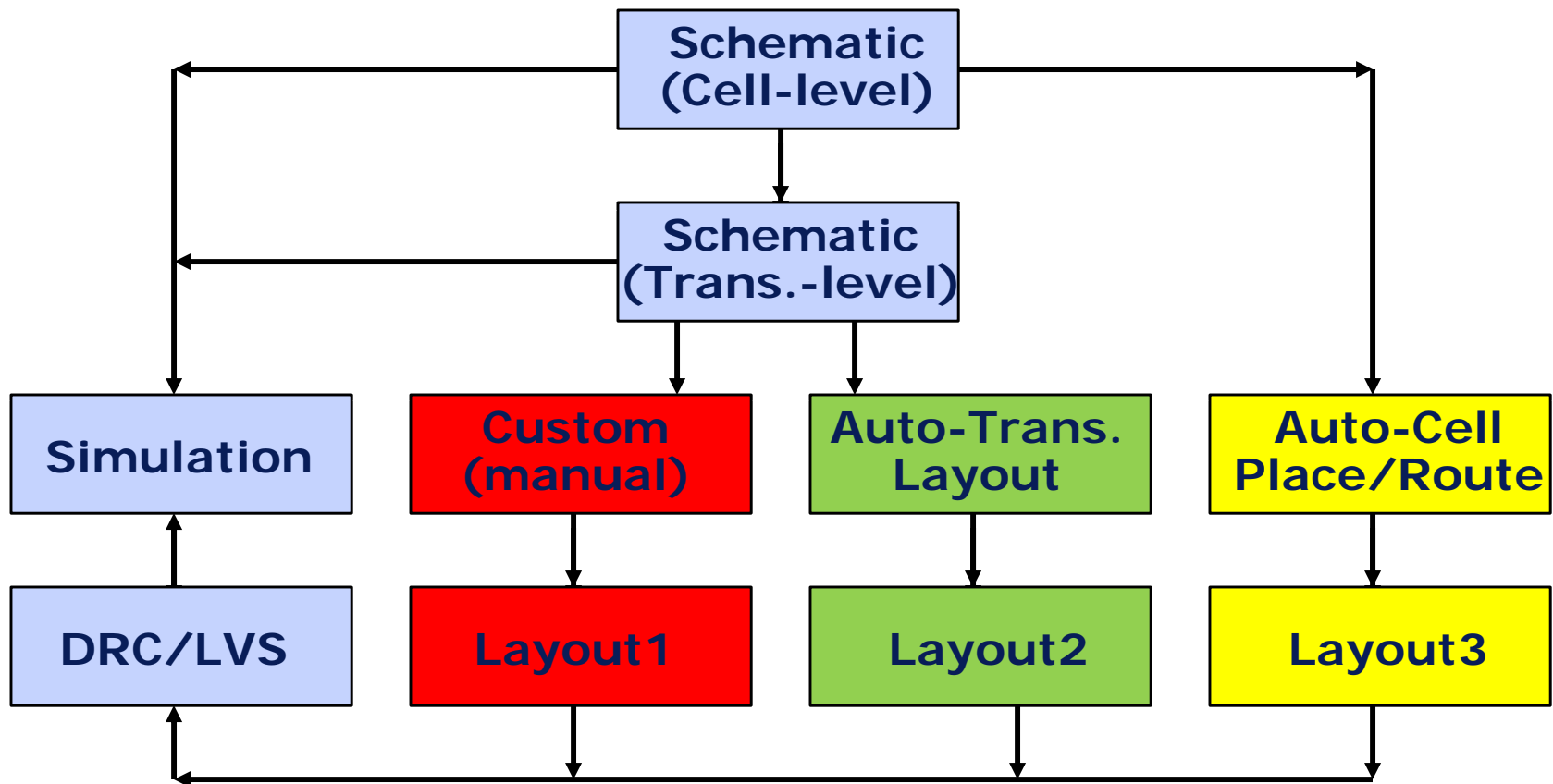
STANDARD-HEIGHT CELL CHIPS CAN ALSO USE EMBEDDED RAM



Space
between
rows for
wiring
can be
varied as
needed.

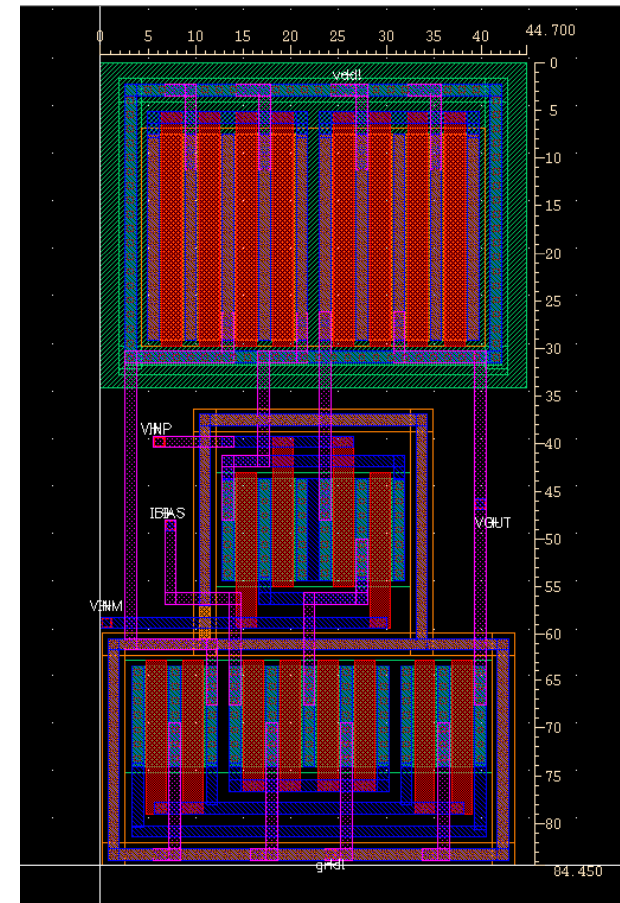


LAYOUT COMPARISONS



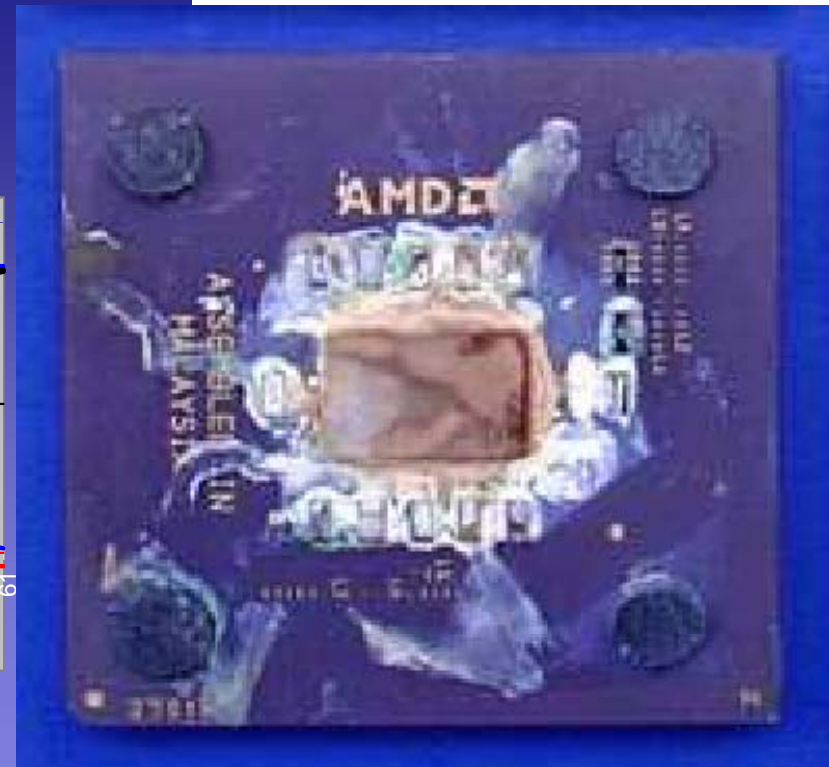
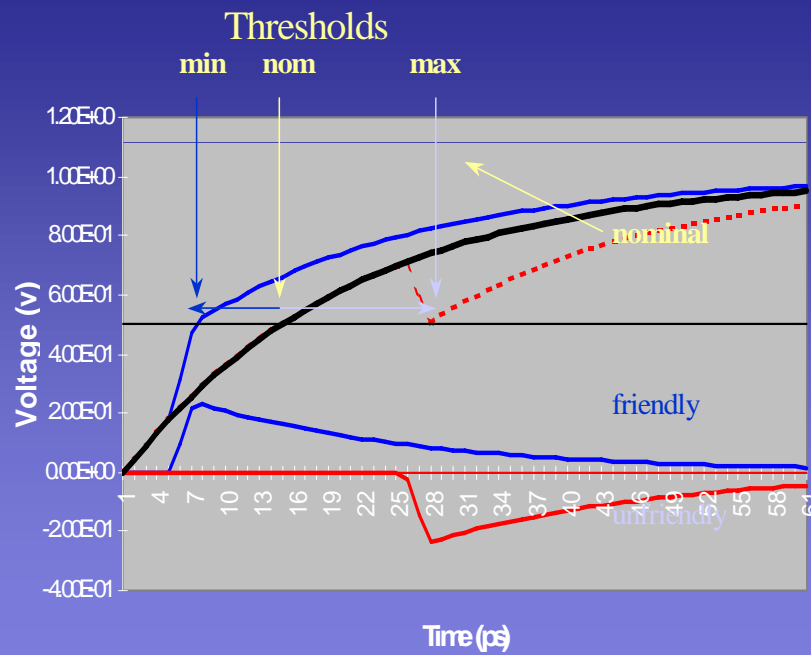
SPECIAL TECHNIQUES ARE USED FOR LAYOUT OF ANALOG CIRCUITS

- Layouts use multi-gate fingers and common-centroid symmetry to improve matching of devices.
- Poly2-Poly1 capacitors save space.
- Switched-capacitor circuits replace large resistors.
- Guard rings reduce noise.



SIGNAL INTEGRITY AND POWER ISSUES ARE ESCALATING

Effects of Crosstalk: Delay Uncertainty



<http://vlsicad.ucsd.edu/>

<http://www.tomshardware.com/>

COURSE GOALS

This **design-oriented** course involves:

- (1) comparison of layout methods (manual vs. two automatic ones)
- (2) nanometer design issues (cross-talk, power, yield)
- (3) with local/remote access to LINUX workstations
- (4) grade depending on homework and final exam
- (5) all presentation slides will be posted on the web:

<http://web.eecs.utk.edu/~bouldin/courses/651/overview.html>